

A, W, H, McL & N Docket No. _____

Declaration For U.S. Patent Application**BEST AVAILABLE COPY**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled
(Insert Title) WIRING SUBSTRATE FOR MOUNTING SEMICONDUCTOR ELEMENTS AND FABRICATING METHOD THEREOF

the specification of which is attached hereto unless the following is checked:

was filed on _____ as United States Application Number or PCT International
Application Number _____ and was amended on _____☐ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) - (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

(List prior foreign applications. See note A on back of this page)

11-141676
(Number)11-229140
(Number)

(Number)

(Number)

Japan

(Country)

Japan

(Country)

(Country)

(Country)

21/5/1999

(Day/Month/Year Filed)

13/8/1999

(Day/Month/Year Filed)

(Day/Month/Year Filed)

(Day/Month/Year Filed)

Priority Claimed

☒ Yes ☐ No☒ Yes ☐ No☐ Yes ☐ No☐ Yes ☐ No

(See note B on back of this page)

☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

(Application Number)

(Filing Date)

(Application Number)

(Filing Date)

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of the application:

(List Prior U.S. Applications)

(Application Serial Number)

(Filing Date)

(Status) (patented, pending, abandoned)

(Application Serial Number)

(Filing Date)

(Status) (patented, pending, abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

James E. Armstrong, III, Reg. No. 18,366; William F. Westerman, Reg. No. 29,988; Ken-Ichi Hattori, Reg. No. 32,861; Le-Nhung McLeland, Reg. No. 31,541; Ronald F. Naughton, Reg. No. 24,616; John R. Pegan, Reg. No. 18,069; William G. Kratz, Jr., Reg. No. 22,631; Albert Tockman, Reg. No. 19,722; Mel R. Quintos, Reg. No. 31,898; Donald W. Hanson, Reg. No. 27,133; Stephen G. Adrian, Reg. No. 32,878; William L. Brooks, Reg. No. 34,129; John F. Carney, Reg. No. 20,276; Edward F. Welsh, Reg. No. 22,455; Patrick D. Muir, Reg. No. 37,403; Gay A. Spahn, Reg. No. 34,978; and John P. Kong, Reg. No. 40,054.

Please direct all communications to the following address:

ARMSTRONG, WESTERMAN, HATTORI,
McLELAND & NAUGHTON
1725 K Street, N.W., Suite 1000
Washington, D.C. 20006
Telephone: (202) 659-2930 Fax: (202) 887-0357

BEST AVAILABLE COPY

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name) Tomoo IIJIMA
(See note C above) Inventor's Signature Tomoo Iijima Date 15/11/1999
Residence Tokyo, Japan Citizenship Japan
Post Office Address c/o North Corporation, 3-37-5 Minami-otsuka, Toshima-ku, Tokyo 170-0005, Japan

Full name of second inventor (given name, family name) Masayuki OOSAWA
Inventor's Signature Masayuki Osawa Date 15/11/1999
Residence Tokyo, Japan Citizenship Japan
Post Office Address c/o North Corporation, 3-37-5 Minami-otsuka, Toshima-ku, Tokyo 170-0005, Japan

Full name of third inventor (given name, family name) Shigeo HIRADE
Inventor's Signature Shigeo Hirade Date 15/11/1999
Residence Tokyo, Japan Citizenship Japan
Post Office Address c/o North Corporation, 3-37-5 Minami-otsuka, Toshima-ku, Tokyo 170-0005, Japan

Full name of fourth inventor (given name, family name) _____
Inventor's Signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of fifth inventor (given name, family name) _____
Inventor's Signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of sixth inventor (given name, family name) _____
Inventor's Signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of seventh inventor (given name, family name) _____
Inventor's Signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of eighth inventor (given name, family name) _____
Inventor's Signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____